

#### C2225X392JGGAC

SMD Comm COG HV Flex, Ceramic, 3900 pF, 5%, 2000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 2225



Click here for the 3D model.

| Dimensions |                 |
|------------|-----------------|
| Chip Size  | 2225            |
| L          | 5.9mm +/-0.75mm |
| W          | 6.4mm +/-0.4mm  |
| T          | 2.5mm +/-0.20mm |
| В          | 0.7mm +/-0.35mm |

| Packaging Specifications |           |  |
|--------------------------|-----------|--|
| Packaging                | Bulk, Bag |  |
| Packaging Quantity       | 1         |  |

| General Information |                                 |
|---------------------|---------------------------------|
| Series              | SMD Comm COG HV Flex            |
| Style               | SMD Chip                        |
| Description         | SMD, MLCC, FT-CAP, Ultra-Stable |
| Features            | FT-CAP, Ultra-Stable            |
| RoHS                | Yes                             |
| Termination         | Flexible Termination            |
| Marking             | No                              |
| AEC-Q200            | No                              |
| Component Weight    | 390 mg                          |
| Shelf Life          | 78 Weeks                        |
| MSL                 | 1                               |

| Specifications   | ,                         |
|--|---------------------------|
| Capacitance  | 3900 pF                   |
| Measurement Condition  | 1 kHz 1.0Vrms             |
| Capacitance Tolerance  | 5%                        |
| Voltage DC   | 2000 VDC                  |
| Dielectric Withstanding Voltage                                    | 2400 VDC                  |
| Temperature Range  | -55/+125°C                |
| Temperature Coefficient  | COG                       |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz<br>1.0Vrms |
| Dissipation Factor   | 0.1% 1 kHz 1.0Vrms        |
| Aging Rate   | 0% Loss/Decade<br>Hour    |
| Insulation Resistance  | 100 GOhms                 |

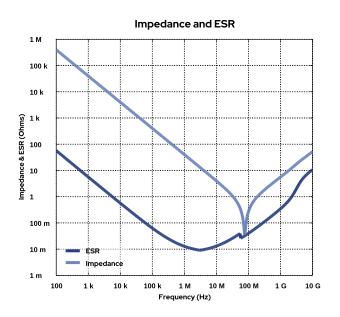
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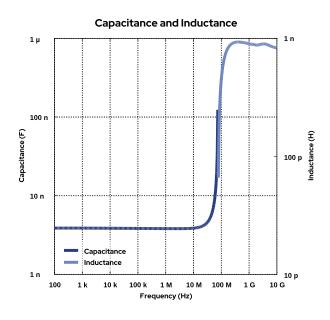


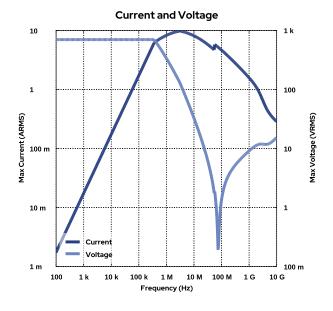
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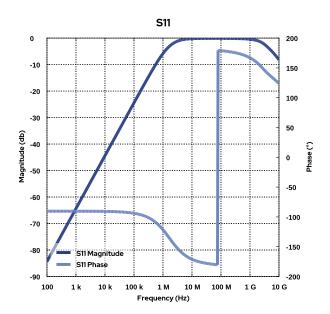
## **Simulations**

For the complete simulation environment please visit K-SIM.





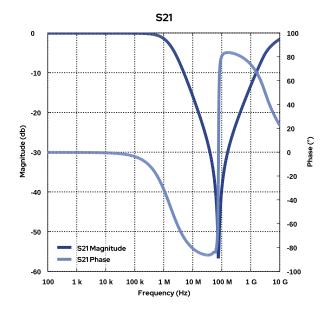






### C2225X392JGGAC

SMD Comm C0G HV Flex, Ceramic, 3900 pF, 5%, 2000 VDC, C0G, SMD, MLCC, FT-CAP, Ultra-Stable, 2225





#### C2225X392JGGAC

SMD Comm COG HV Flex, Ceramic, 3900 pF, 5%, 2000 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 2225

#### These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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